

# IGBT Modules

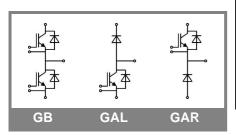
SKM 300GB123D SKM 300GAL123D SKM 300GAR123D

#### **Features**

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I<sub>cnom</sub>
- · Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology
- Large clearance (12 mm) and creepage distance (20 mm)

#### **Typical Applications**

- AC inverter drives
- UPS



Absolute Maximum Ratings T <sub>c</sub> = 25 °C, unless otherwise :				pecified
Symbol	Conditions		Values	Units
IGBT				
$V_{CES}$	T <sub>j</sub> = 25 °C		1200	V
I <sub>C</sub>	T <sub>j</sub> = 150 °C	T <sub>case</sub> = 25 °C	300	Α
		T <sub>case</sub> = 80 °C	220	Α
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		400	Α
$V_{GES}$			± 20	V
t <sub>psc</sub>	$V_{CC}$ = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V	T <sub>j</sub> = 125 °C	10	μs
Inverse D	Diode			•
I <sub>F</sub>	T <sub>j</sub> = 150 °C	$T_{case}$ = 25 °C	260	Α
		T <sub>case</sub> = 80 °C	180	Α
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		400	Α
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	2200	Α
Freewhee	eling Diode			•
I <sub>F</sub>	T <sub>j</sub> = 150 °C	$T_{case}$ = 25 °C	350	Α
		T <sub>case</sub> = 80 °C	230	Α
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		600	Α
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin	T <sub>j</sub> = 150 °C	2900	Α
Module				•
$I_{t(RMS)}$			500	Α
T <sub>vj</sub>			- 40+ 150	°C
T <sub>stg</sub>			- 40+ 125	°C
V <sub>isol</sub>	AC, 1 min.		2500	V

Characteristics T <sub>c</sub> =		25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{\text{GE(th)}}$	$V_{GE} = V_{CE}$ , $I_{C} = 8 \text{ mA}$		4,5	5,5	6,5	V
I <sub>CES</sub>	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T <sub>j</sub> = 25 °C		0,1	0,3	mA
$V_{CE0}$		T <sub>j</sub> = 25 °C		1,4	1,6	V
		T <sub>j</sub> = 125 °C		1,6	1,8	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		5,5	7	mΩ
		T <sub>j</sub> = 125°C		7,5	9,5	$m\Omega$
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 200 A, V <sub>GE</sub> = 15 V			2,5	3	V
		$T_j = 125^{\circ}C_{chiplev}$		3,1	3,7	V
C <sub>ies</sub>				18	24	nF
C <sub>oes</sub>	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		2,5	3,2	nF
C <sub>res</sub>				1	1,3	nF
$Q_G$	-8V - +20V			2000		nC
R <sub>Gint</sub>	T <sub>j</sub> = °C			2,5		Ω
t <sub>d(on)</sub>				250	400	ns
t <sub>r</sub>	$R_{Gon} = 4.7 \Omega$	V <sub>CC</sub> = 600V		90	160	ns
E <sub>on</sub>		I <sub>Cnom</sub> = 200A		28		mJ
t <sub>d(off)</sub>	$R_{Goff} = 4.7 \Omega$	T <sub>j</sub> = 125 °C		550	700	ns
t <sub>f</sub>				70	100	ns
E <sub>off</sub>				26		mJ
R <sub>th(j-c)</sub>	per IGBT				0,075	K/W



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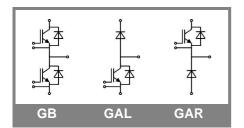
#### **Typical Applications**

- AC inverter drives
- UPS

Characteristics						
Symbol	Conditions		min.	typ.	max.	Units
Inverse D						
$V_F = V_{EC}$	I <sub>Fnom</sub> = 200 A; V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		2	2,5	V
$V_{F0}$		T <sub>j</sub> = 25 °C		1,1	1,2	V
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$				V
r <sub>F</sub>				4,5	6,5	mΩ
		T <sub>j</sub> = 125 °C				mΩ
I <sub>RRM</sub>	I <sub>Fnom</sub> = 200 A	T <sub>j</sub> = 125 °C		105		Α
Q <sub>rr</sub>	di/dt = 4000 A/μs			10		μC
E <sub>rr</sub>	V <sub>GE</sub> = 0 V; V <sub>CC</sub> = 600 V					mJ
R <sub>th(j-c)D</sub>	per diode				0,18	K/W
Freewhee	ling Diode					
$V_F = V_{EC}$	I <sub>Fnom</sub> = 300 A; V <sub>GE</sub> = 0 V	$T_j = 25  ^{\circ}C_{\text{chiplev.}}$		2	2,5	V
$V_{F0}$		T <sub>j</sub> = 25 °C		1,1	1,2	V
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 25 ^{\circ}\text{C}$				V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		3	4,3	V
		$T_j = 125 ^{\circ}\text{C}$ $T_j = 125 ^{\circ}\text{C}$				V
I <sub>RRM</sub>	I <sub>Fnom</sub> = 200 A	T <sub>j</sub> = 125 °C		140		A
Q <sub>rr</sub>	di/dt = 3500 A/µs			34		μC
E <sub>rr</sub>	V <sub>GE</sub> = 0 V; V <sub>CC</sub> = 600 V					mJ
R <sub>th(j-c)FD</sub>	per diode				0,15	K/W
Module						
L <sub>CE</sub>				15	20	nΗ
R <sub>CC'+EE'</sub>	res., terminal-chip	T <sub>case</sub> = 25 °C		0,35		mΩ
		T <sub>case</sub> = 125 °C		0,5		mΩ
R <sub>th(c-s)</sub>	per module				0,038	K/W
M <sub>s</sub>	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.





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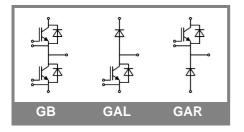
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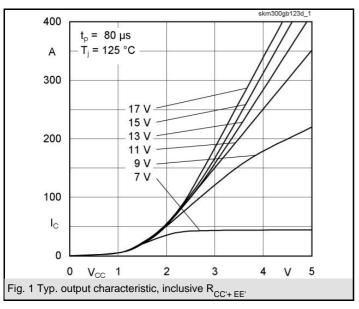
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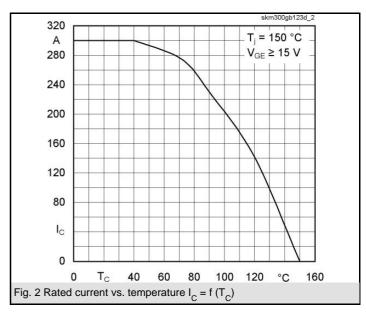
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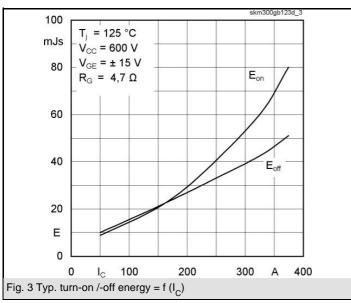
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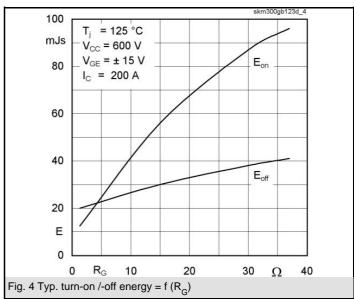


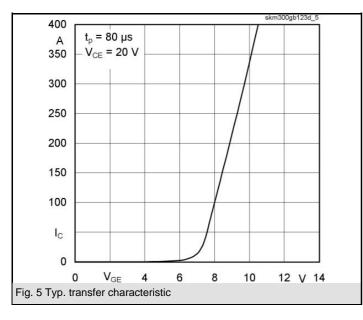
Z <sub>th</sub> Symbol	Conditions	Values	Units
Z <sub>th(j-c)l</sub>			
R <sub>i</sub>	i = 1	53	mk/W
$R_i$	i = 2	18,5	mk/W
Ri	i = 3	3,1	mk/W
$R_{i}$	i = 4	0,4	mk/W
tau <sub>i</sub>	i = 1	0,04	s
tau <sub>i</sub>	i = 2	0,0189	s
tau <sub>i</sub>	i = 3	0,0017	s
tau <sub>i</sub>	i = 4	0,003	s
Z <sub>th(j-c)D</sub>			·
R <sub>i</sub>	i = 1	0,1151	mk/W
$R_i$	i = 2	0,0525	mk/W
$R_i$	i = 3	0,0111	mk/W
R <sub>i</sub>	i = 4	0,0022	mk/W
tau <sub>i</sub>	i = 1	0,0366	s
tau <sub>i</sub>	i = 2	0,0113	s
tau <sub>i</sub>	i = 3	0,003	s
tau <sub>i</sub>	i = 4	0,0002	s

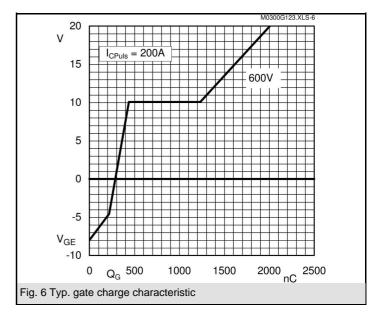


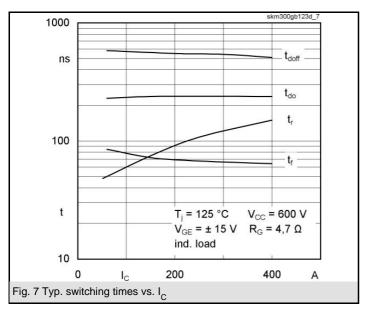


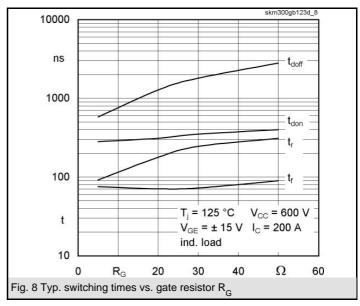


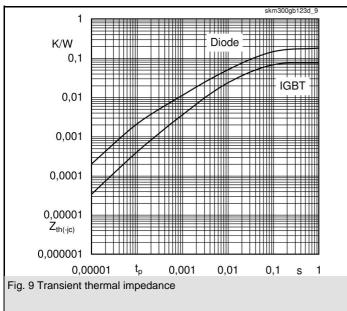


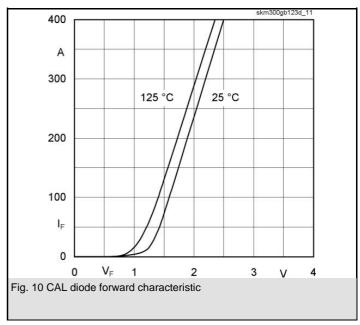


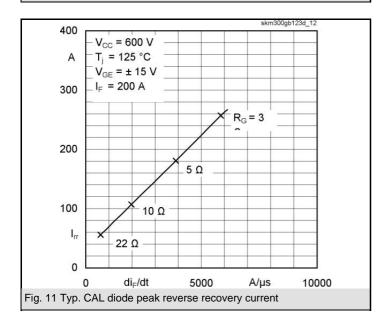


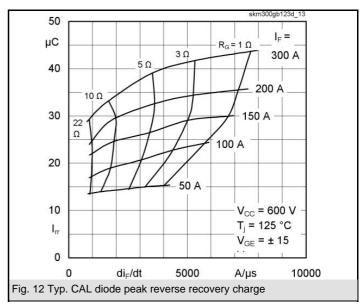








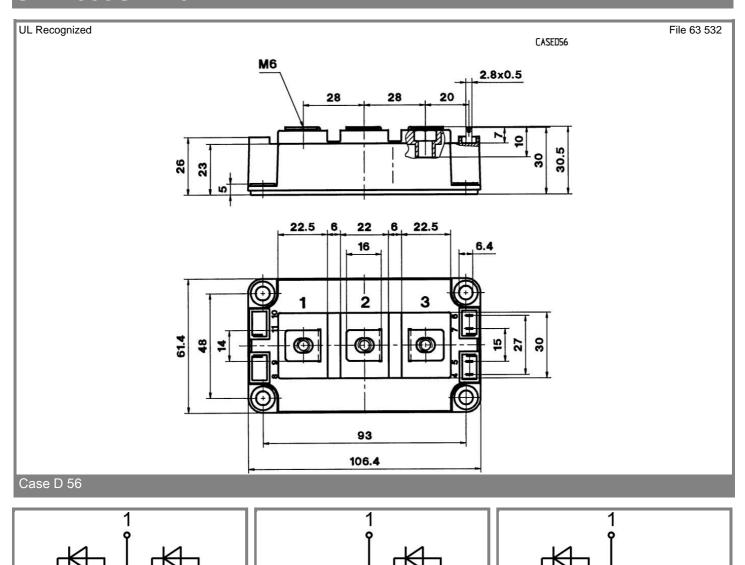




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Case D 56

GAL



Case D 57 (→ D 56)

GAR

Case D 58 (→ D 56 )